PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Mou-Shiung Lin	06/03/2008
JIN-YUAN Lee	06/03/2008

RECEIVING PARTY DATA

Name:	MEGICA CORPORATION
Street Address:	Room 301/302, No. 47, Park 2nd Rd.,
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12138453

OP $40.00 12138453

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	MSL98-002-CIP-E02
NAME OF SUBMITTER:	MarsYang

Total Attachments: 2
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ASSIGNMENT

WHEREAS,

1. Mou-Shiung Lin 2. Jin-Yuan Lee

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **TOP LAYERS OF METAL FOR HIGH PERFORMANCE IC'S**

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Megica Corporation
of Room 301/302, No.47, Park 2nd Rd., Science-Based Industrial Park Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature:______________ Date: June 3, 2008

Sole or First Joint Inventor: Mou-Shiung Lin

Signature: Jin-Yuan Lee Date: Jun 3 2008

Second Joint Inventor(if any): Jin-Yuan Lee